

Call for Papers

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The SISC is a workshop-style conference that provides a forum for device engineers, solid state physicists, and material scientists to discuss topics of common interest, formally through invited and contributed presentations, and informally during poster and rump sessions. SISC is sponsored by the IEEE Electron Devices Society and is held right after IEDM.

The program includes talks and poster presentations (*theory and experiment*) from all areas of semiconductor interface science and technology, including but not limited to:

- Insulators on **high-mobility** and **alternative substrates** (SiGe, Ge, III-V and III-N, SiC, etc.)
- **2D materials** and devices
- **Steep slope logic devices** including “**negative capacitance**” gates, ferroelectric HfO₂, tunnel FETs
- **Non-volatile memory materials**, including their application to **in-memory compute** and **AI**
- **Electrical characterization, performance, and reliability** of MOS-based devices
- Dielectrics on **nanowires/-tubes**
- **Oxide electronics** and **multiferroics**
- Interfaces in **photovoltaics**, e.g., semiconductor passivation
- Interfaces in **semiconductor lighting** and **optical communications**
- Interfaces and surfaces in **biotechnology** such as **bio-sensing**
- **Neuromorphic** and **quantum computing**

Confirmed Invited speakers

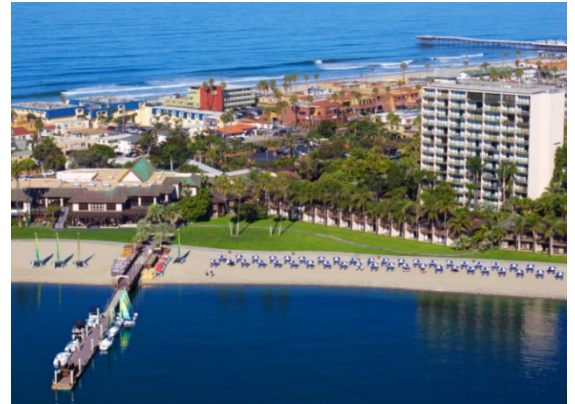
- **Dr. Takashi Ando**, IBM, USA
Hardware Algorithm Co-optimization for Scalable Analog Compute Technology
- **Dr. Hiroaki Arimura**, imec, Belgium
Gate Stack Technology for Advanced Logic and Memory Periphery Devices
- **Prof. Gong Cheng**, U. Maryland, USA
Controlling 2D magnetism for efficient spintronics
- **Dr. Nick Chiang**, TSMC, Taiwan
Device engineering and benefit maximization for advanced cryo-CMOS
- **Prof. Asif I. Khan**, Georgia Tech, USA
Reliability of ferroelectric field-effect transistors
- **Prof. John Robertson**, U. Cambridge, UK
Reduced contact resistances for Moire Lattice Interfaces of MoS₂ and other Layered Compounds
- **Prof. Gong Xiao**, National University of Singapore, Singapore
Oxide Semiconductor Back-end-of-line (BEOL)-Compatible Transistors and Memories
- **Prof. Grace Xing**, Cornell U., USA
Heterointerfaces in the AlN material system

Wednesday evening Tutorial

- **Prof. Ashraf Alam**, Purdue U., USA
Reliability Physics in Post-Moore Era Electronics: Material, Devices, and System Perspective

A **Best Student Presentation Award** will be given in memory of E. H. Nicollian.

A **Best Poster Award** will be given in memory of T. P. Ma.



Abstract submission deadline August 1, 2022